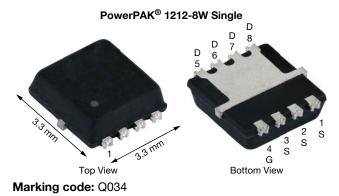
# SQS482ENW

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**Vishay Siliconix** 

# Automotive N-Channel 30 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY					
V <sub>DS</sub> (V)	30				
$R_{DS(on)} (\Omega)$ at $V_{GS} = 10 V$	0.0085				
$R_{DS(on)} (\Omega)$ at $V_{GS} = 4.5 V$	0.0100				
I <sub>D</sub> (A)	16				
Configuration	Single				
Package	PowerPAK 1212-8W				

#### FEATURES

- TrenchFET<sup>®</sup> power MOSFET
- AEC-Q101 qualified <sup>d</sup>
- 100 % R<sub>g</sub> and UIS tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

GO

D



RoHS COMPLIANT HALOGEN FREE

Configuration Package	Single PowerPAK 1212-8W		N-Channel MOSFET			
ABSOLUTE MAXIMU	M RATINGS (T <sub>C</sub> = 25 °	C, unless otherwise n	oted)			
PARAMETER		SYMBOL	LIMIT	UNI		
Drain-source voltage		V <sub>DS</sub>	30	V		
Gate-source voltage		V <sub>GS</sub>	± 20	V		
	T <sub>C</sub> =	= 25 °C	16			
Continuous drain current <sup>a</sup>	T <sub>C</sub> =	125 °C	16	A		
Continuous source current (c	liode conduction) <sup>a</sup>	I <sub>S</sub>	16			
Pulsed drain current <sup>b</sup>		I <sub>DM</sub>	64			
Single pulse avalanche current		D.1 mH	31			
Single pulse avalanche energ	IV L = V	E <sub>AS</sub>	48	mJ		
Maximum power dissipation	b T <sub>C</sub> =	= 25 °C	62	W		
waximum power dissipation	T <sub>C</sub> =	125 °C P <sub>D</sub>	20			
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C		
Soldering recommendations	(peak temperature) <sup>e, f</sup>		260	-0		

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-ambient	PCB mount <sup>c</sup>	R <sub>thJA</sub>	81	°C/W
Junction-to-case (drain)		R <sub>thJC</sub>	2.4	C/VV

#### Notes

- a. Package limited
- b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %
- c. When mounted on 1" square PCB (FR4 material)
- d. Parametric verification ongoing
- e. See solder profile (<u>www.vishay.com/doc?73257</u>). The PowerPAK 1212-8W is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- f. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components

# SQS482ENW

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PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static	•					•	
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub>	= 0, I <sub>D</sub> = 250 μA	30	-	-	v
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μΑ	1.5	2.0	2.5	v
Gate-source leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	$0 V, V_{GS} = \pm 20 V$	-	-	± 100	nA
		$V_{GS} = 0 V$	V <sub>DS</sub> = 30 V	-	-	1	
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 30 V, T <sub>J</sub> = 125 °C	-	-	50	μA
		$V_{GS} = 0 V$	V <sub>DS</sub> = 30 V, T <sub>J</sub> = 175 °C	-	-	150	1
On-state drain current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	20	-	-	Α
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 16.4 A	-	0.0070	0.0085	
Durain acturate an atota register as 3	Б	$V_{GS} = 10 V$	I <sub>D</sub> = 16.4 A, T <sub>J</sub> = 125 °C	-	-	0.0135	0
Drain-source on-state resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 10 V$	I <sub>D</sub> = 16.4 A, T <sub>J</sub> = 175 °C	-	-	0.0160	Ω
		$V_{GS} = 4.5 V$	I <sub>D</sub> = 16.4 A	-	0.0080	0.0100	
Forward transconductance b	<b>g</b> fs	V <sub>DS</sub> =	= 15 V, I <sub>D</sub> = 16.4 A	-	70	-	S
Dynamic <sup>b</sup>							
Input capacitance	C <sub>iss</sub>			-	1492	1865	
Output capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 25 V, f = 1 MHz	-	280	350	pF
Reverse transfer capacitance	C <sub>rss</sub>			-	108	135	
Total gate charge <sup>c</sup>	Qg			-	26	39	
Gate-source charge <sup>c</sup>	Q <sub>gs</sub>	$V_{GS} = 10 V$	$V_{DS} = 15 \text{ V}, I_D = 10 \text{ A}$	-	4.7	-	nC
Gate-drain charge <sup>c</sup>	Q <sub>gd</sub>			-	4.3	-	
Gate resistance	R <sub>g</sub>		f = 1 MHz	5	10	20	Ω
Turn-on delay time <sup>c</sup>	t <sub>d(on)</sub>			-	7	11	
Rise time <sup>c</sup>	t <sub>r</sub>	V <sub>DD</sub>	= 15 V, $R_L$ = 3 $\Omega$	-	21	32	
Turn-off delay time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 5 A,$	$V_{GEN}$ = 10 V, $R_g$ = 1 $\Omega$	-	49	74	ns
Fall Time <sup>c</sup>	t <sub>f</sub>	1		-	18	27	
Source-Drain Diode Ratings and Char	acteristics <sup>b</sup>						
Pulsed current <sup>a</sup>	I <sub>SM</sub>			-	-	64	Α
Forward voltage	V <sub>SD</sub>	١F	= 15 A, V <sub>GS</sub> = 0	-	0.82	1.2	V

Notes

a. Pulse test; pulse width  $\leq 300~\mu\text{s},$  duty cycle  $\leq 2~\%$ 

b. Guaranteed by design, not subject to production testing

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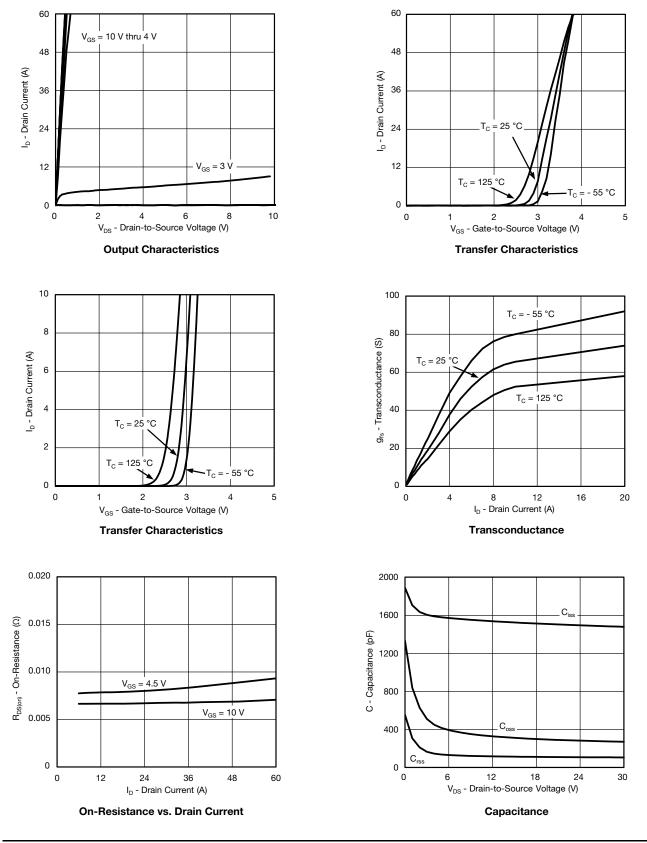
c. Independent of operating temperature

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

2



#### **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



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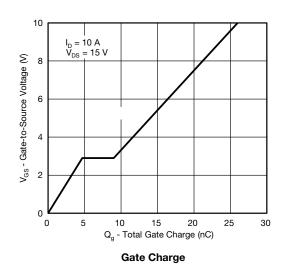
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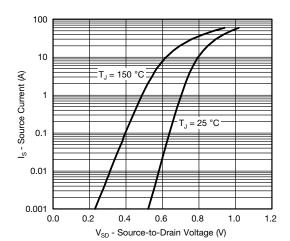
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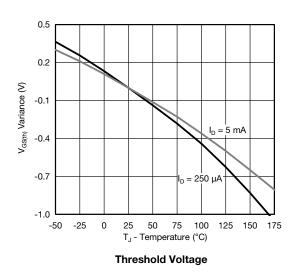


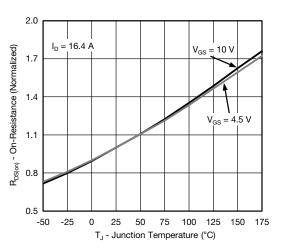
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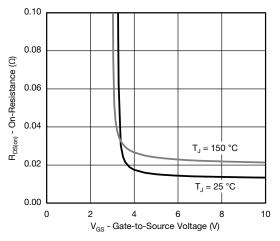


Source Drain Diode Forward Voltage

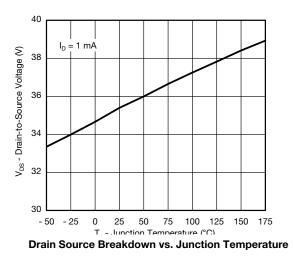




**On-Resistance vs. Junction Temperature** 



**On-Resistance vs. Gate-to-Source Voltage** 



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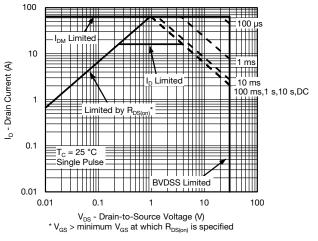
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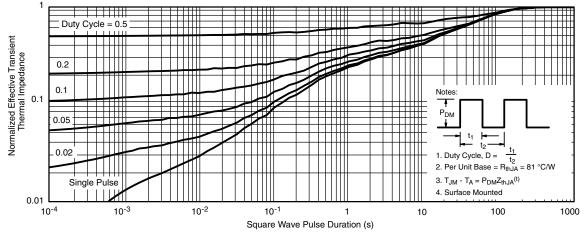
SQS482ENW

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#### **THERMAL RATINGS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)





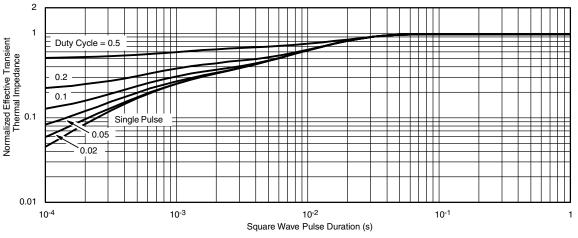


Normalized Thermal Transient Impedance, Junction-to-Ambient



Document Number: 75543

#### **THERMAL RATINGS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

• The characteristics shown in the two graphs

S17-1217-Rev. A, 07-Aug-17

- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

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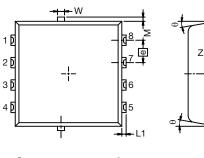
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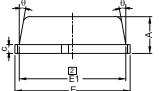


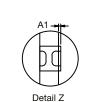
# PowerPAK<sup>®</sup> 1212-8W Case Outline

Δ2

224



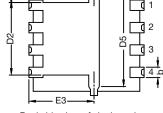




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Б



E2

E4

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Notes
1 Inch will govern

 Dimensions exclusive of mold gate burrs
 Dimensions exclusive of mold flash and cutting burrs

DIM.	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	IIN. NOM.		
А	0.97	1.04	1.12	0.038	0.041	0.044	
A1	0	-	0.05	0	-	0.002	
A2	0	-	0.13	0	-	0.005	
b	0.23	0.30	0.41	0.009	0.012	0.016	
С	0.23	0.28	0.33	0.009	0.011	0.013	
D	3.20	3.30	3.40	0.126	0.130	0.134	
D1	2.95	3.05	3.15	0.116	0.120	0.124	
D2	1.98	2.11	2.24	0.078	0.083	0.088	
D4	0.47 typ.			0.0185 typ.			
D5	2.3 typ.			0.090 typ.			
E	3.20	3.30	3.40	0.126	0.130	0.134	
E1	2.95	3.05	3.15	0.116	0.120	0.124	
E2	1.47	1.60	1.73	0.058	0.063	0.068	
E3	1.75	1.85	1.98	0.069	0.073	0.078	
E4	0.34 typ.			0.013 typ.			
е	0.65 BSC.			0.026 BSC			
К	0.86 typ.			0.034 typ.			
Н	0.30	0.41	0.51	0.012	0.016	0.020	
L	0.30	0.43	0.56	0.012	0.017	0.022	
L1	0.06	0.13	0.20	0.002	0.005	0.008	
θ	0°	-	12°	0°	-	12°	
W	0.15	0.25	0.36	0.006	0.010	0.014	
М	0.125 typ.			0.005 typ.			
N: C15-1530-R	ev. B, 16-Nov-15						

Backside view of single pad



### RECOMMENDED MINIMUM PADS FOR PowerPAK<sup>®</sup> 1212-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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